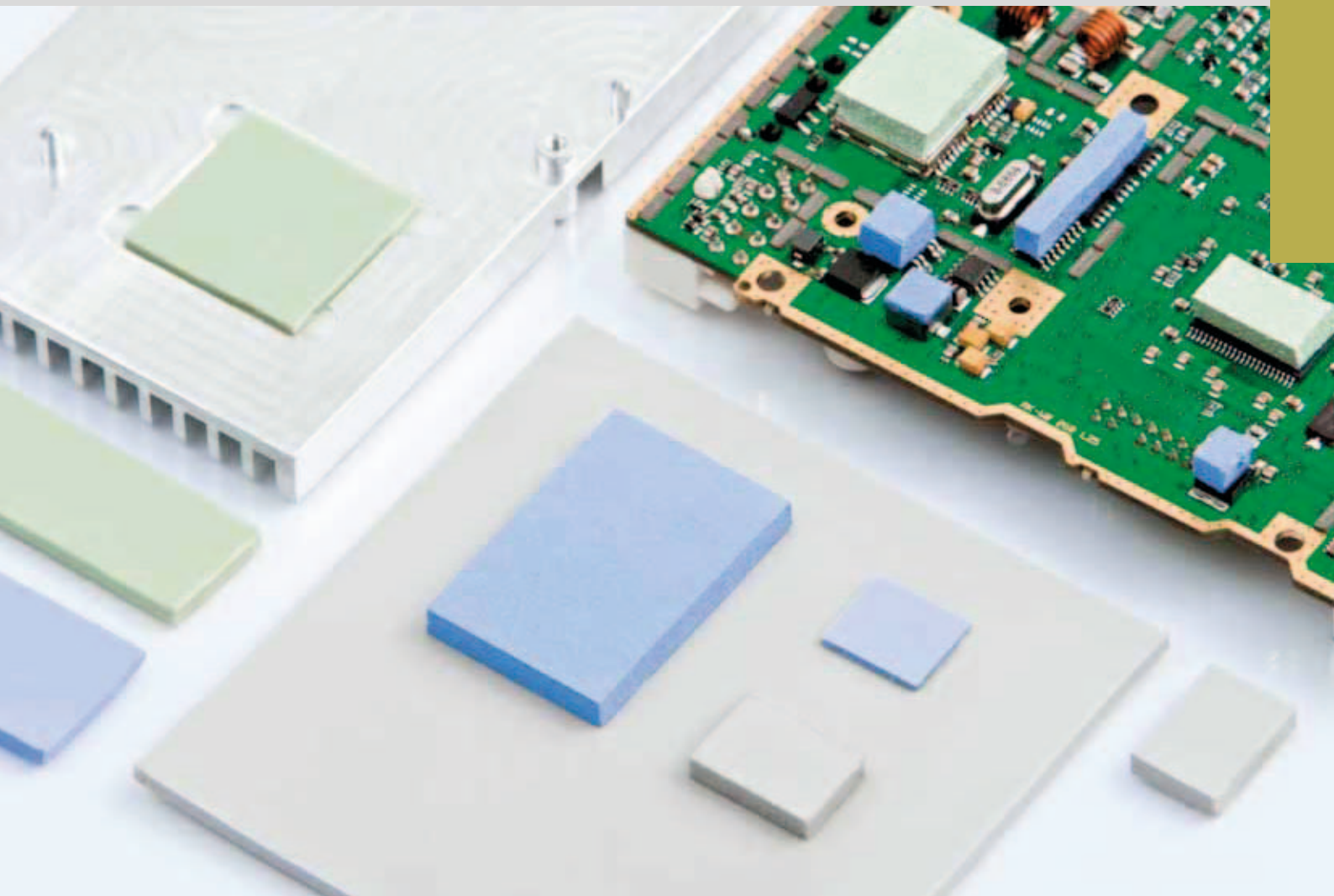


1.

**GAP
FILLER.**



GENERAL INFORMATION

This product family is used to fill air gaps between hot components and heat sinks or metal chassis.

Their flexible, elastic nature allows them to blanket highly uneven surfaces.

Gap Fillers are used where high thermal conductivity and low pressure are required.

We offer the softest, highest thermally conductive gap fillers available (in thickness from 0.5mm to 5.0 mm and up).

Our **Gap Fillers** are soft and very compliant. They afford designers the most flexibility in dimensional tolerancing.

Extreme compliancy reduces stress on the components while higher thermal conductivity provides the thermal performance required.

Customizations



FEATURES AND BENEFITS

- Thermal Conductivity Range from 0.8 to 6.0 W/mK.
- Thickness from 0.5 to 5.0 mm and up.
- Compliancy-rates up to 60 % deflection at 50 psi.
- Extreme Softness from 05 Shore 00.
- Natural Tacky on one or on both sides.
- Flammability rating up to UL94 V0.

EXAMPLES OF APPLICATIONS

- Notebook Computers, Handheld Portable Micro Processors.
- Telecommunications Hardware.
- Semiconductor Test Equipment, Servers-Desktop Computers.
- High Speed Mass Storage Devices.
- Plasma Supply Panels, Memory Modules.
- Power Conversion Equipment, Audio & Video Components.